



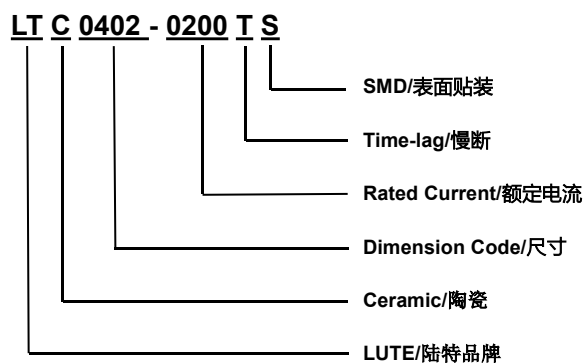
Description/描述

LTC0402TS Series are time-lag fuse, the chip fuses set the industry standard for performance, reliability and quality. The solder-free design provides excellent on-off and temperature cycling characteristics and also makes our chip fuses more heat and shock tolerant than typical subminiature fuses.

Features/特征

- Time-lag for excessive current
- Compatible with reflow and wave solder
- Ceramic and glass construction
- Excellent environmental integrity
- One time positive disconnect
- Lead Free and Halogen free material

Part Number System/产品编号



Electrical Characteristics/电气特性

% of Rated Current	Rated Current	Opening Time
100%	200mA~4A	4 hours, Minimum
250%	1A~4A	30 seconds, Maximum
350%	200mA~750mA	30 seconds, Maximum

Performance Specifications/电性参数

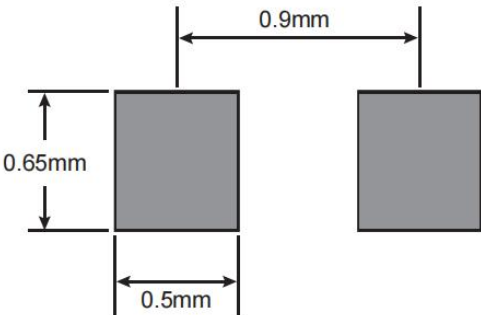
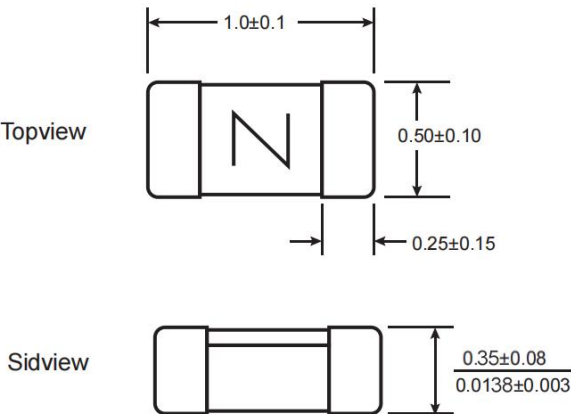
Part Number	Rated Current (A)	Rated Voltage DC	Interrupting Rating	Cold Resistance (mΩ)	Typical Melting I ² t (A ² sec)
LTC0402-0200TS	0.20	32V	35A	2130	0.00068
LTC0402-0250TS	0.25			1352	0.0013
LTC0402-0315TS	0.315			936	0.0016
LTC0402-0375TS	0.375			713	0.0021
LTC0402-0500TS	0.50			458	0.0047
LTC0402-0750TS	0.75			202	0.013
LTC0402-1100TS	1.00			123	0.045
LTC0402-1150TS	1.50			73	0.071
LTC0402-1200TS	2.00			36	0.15
LTC0402-1250TS	2.50			22	0.23
LTC0402-1300TS	3.00			16	0.37
LTC0402-1350TS	3.50			12	0.51
LTC0402-1400TS	4.00			9.8	0.68

- DC Interrupting Rating (Measured at rated voltage, time constant of less than 50 microseconds, battery source)
- DC Cold Resistance are measured at <10% of rated current in ambient temperature of 25°C
- Typical Melting I²t (Measured with a battery bank at rated DC voltage, Measured at 1ms open time, time constant of calibrated circuit less than 50 microseconds).

Product Dimensions (mm)/产品尺寸

Drawing not to scale (Unit:mm/inch)

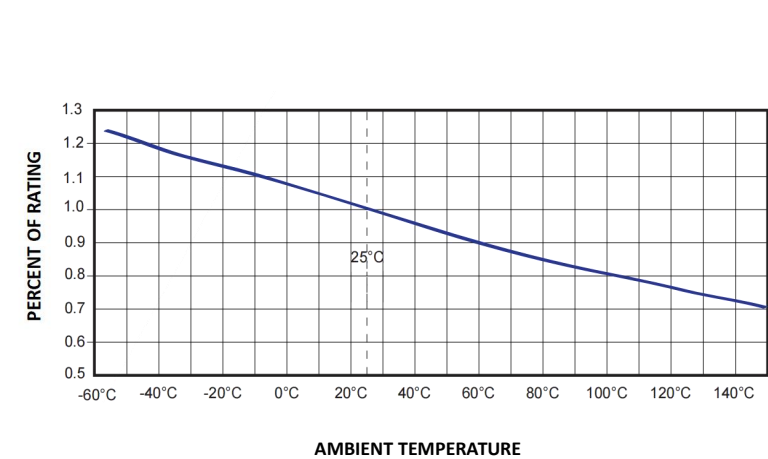
Recommended land pattern:



Print solder in thickness of 0.08mm to 0.10mm

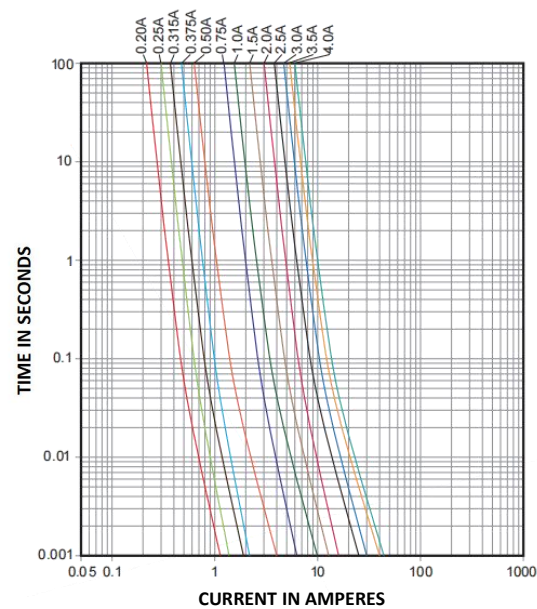
Environmental Characteristic/环境温度特性图

Temperature Derating Curve

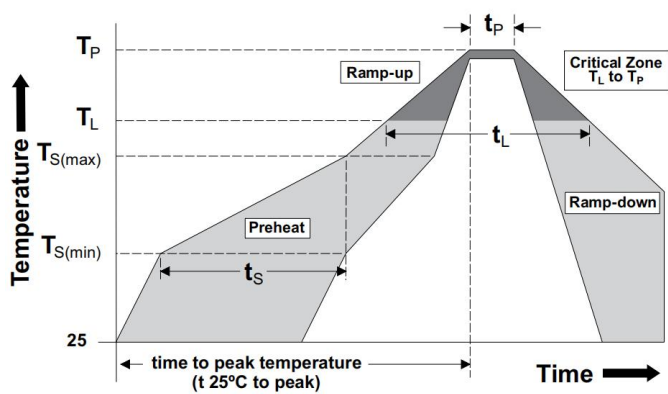


- Normal ambient temperature: 23+/-3°C
- Operating temperature: -55 ~ 150°C, with proper correction factor applied.

Average Time-Current Curve



Soldering Parameters/焊接参数



Soldering Method		Parameter
Wave Solder	Reservoir Temperature	260°C
	Time in Reservoir	10 seconds max
Infrared reflow	Temperature	260°C
	Time	30 seconds max

Profile Feature 特征		Pb-Free Assembly 无铅焊锡
Average Ramp-Up Rate (T _{S(max)} to T _P) 平均升温速度		3°C/second max
Preheat 预热	-Temperature Min(T _{S(min)}) 最低温度	150°C
	-Temperature Max(T _{S(max)}) 最高温度	200°C
	-Time(T _{S(min)} to T _{S(max)}) 预热时间	60~120 seconds
Reflow 回流焊	-Temperature(T _L) 温度	217°C
	-Time(t _L) 时间	60~150 seconds
Peak Temperature (T _P) 峰值温度		260°C
Ramp-Down Rate 降温		6°C/second max
Time 25°C to Peak Temperature 从 25°C到峰值温度时间		8 minutes max
Time within 5°C of actual peak Temperature (t _P)		30 seconds

Packing/包装

Part Number	Quantity & Packaging Code
LTC0402TS	10000 pcs/reel (8mm tape-and-reel on a 7 inch (178mm) reel per EIA Standard 481)

WARNING

- If in use beyond the requirements of the specifications, must pass through the mutual confirmation !
- If the specification is not appropriate, must through consultation between the two sides and by the company to modify !
- It could be in conformance with another file which made by our company.